

ABSTRACT OF THE DISCLOSURE

A solution jet type fabrication apparatus for fabricating a wiring pattern or a device, the solution jet type fabrication apparatus including a jet head for
5 ejecting a droplet of a solution containing fine particles onto a substrate, so as to form a pattern, by vaporizing a volatile ingredient of the solution, and allowing a solid component to remain on the substrate, wherein the substrate has no liquid absorbing property,
10 wherein the jet head includes a nozzle from which the droplet is ejected, the nozzle being formed from a material that has a greater hardness than that of the fine particles in the solution, wherein the nozzle has a size that is equal to or less than $\Phi 20\mu\text{m}$, the nozzle
15 satisfying a relation of $0.0001 \leq D_p/D_o \leq 0.01$, where D_p represents the diameter of each of the fine particles and D_o represents the diameter of the nozzle, wherein each of the fine particles has a size that is equal to or less than the roughness of a surface of the substrate.